Special Issue

Heterogeneous Integration Electronic Devices

Message from the Guest Editors

This Special Issue aims to explore various aspects of heterogeneous integration, including materials, design, fabrication techniques, and applications, and will showcase the recent trends and challenges in this exciting field, providing a platform for researchers to exchange ideas, collaborate, and push the boundaries of what is possible in the realm of electronics integration. In this Special Issue, original research articles and reviews are welcome. Research areas may include (but are not limited to) the following:

- Materials for Heterogeneous Integration;
- Thermal Management for Heterogeneous Integrated Electronic Devices;
- Design and Modeling of Heterogeneous Integrated Devices;
- Fabrication Techniques for Heterogeneous Integration;
- Characterization and Testing of Heterogeneous Integrated Devices;
- Applications of Heterogeneous Integrated Devices;
- Integration and Interconnect Technologies;
- Challenges and Solutions in Heterogeneous Integration;
- Reliability and Lifetime Assessment.

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About the Journal

Message from the Editor-in-Chief

Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guestedited by leading experts in selected topics of interest.

Editor-in-Chief

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